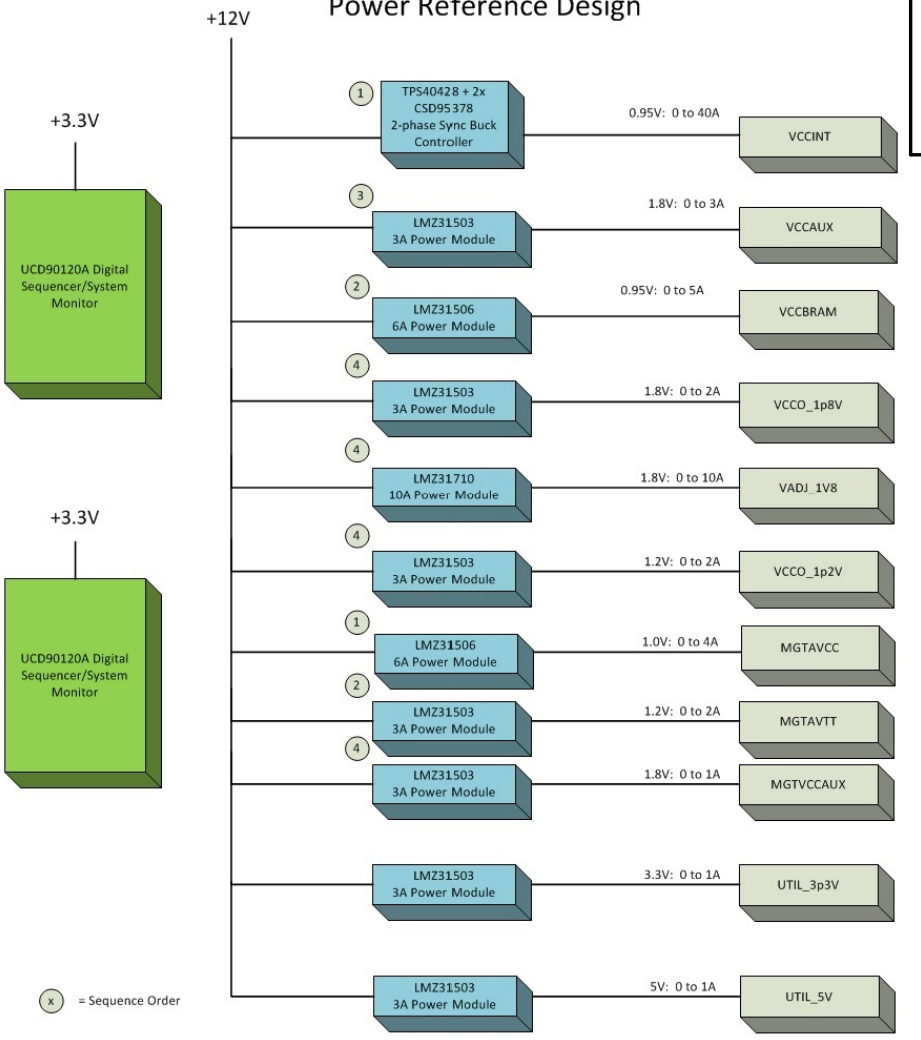
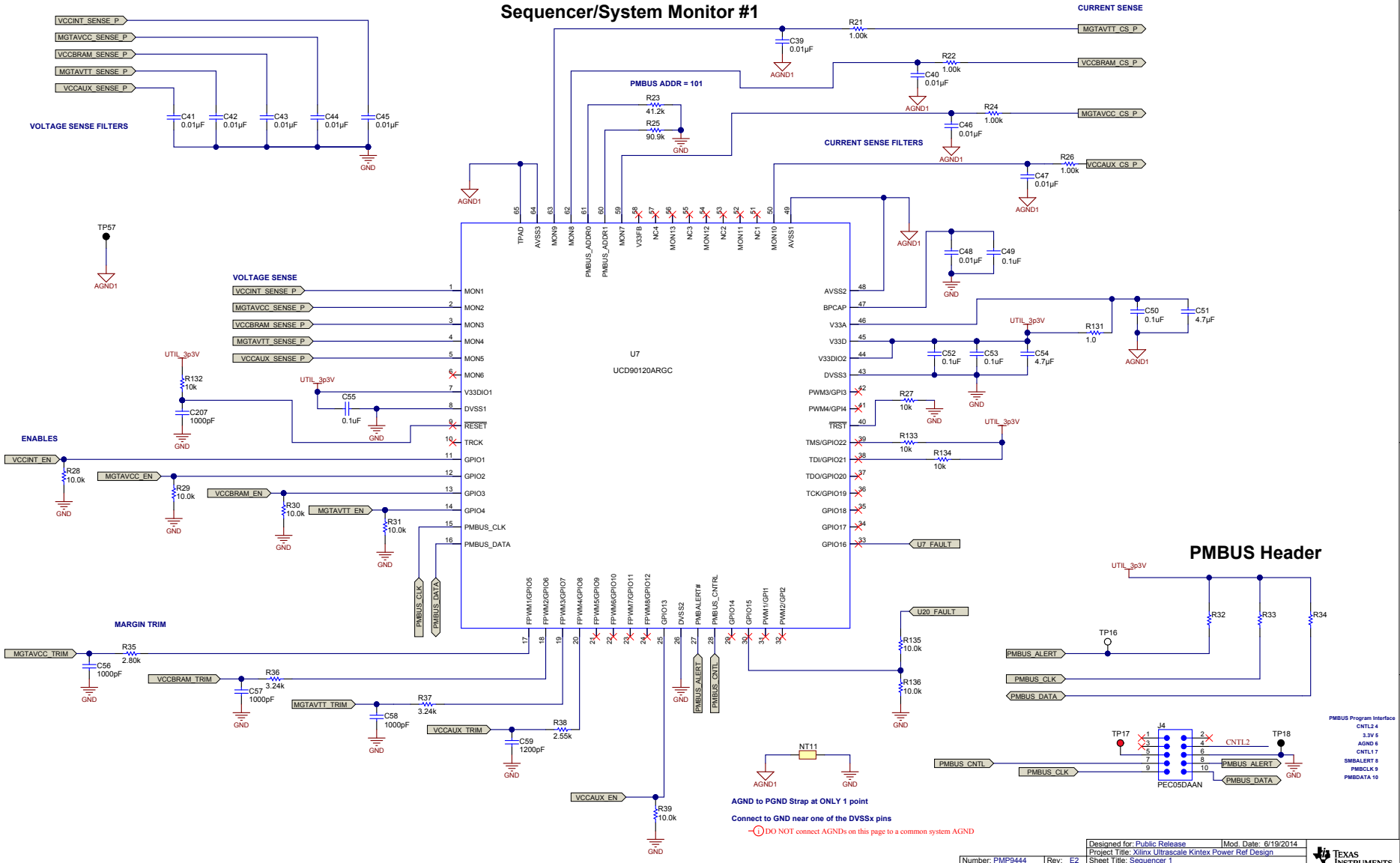
PMP9444 Ultrascale Kintex FPGA Power Reference Design



Revision History	
Revision	Notes

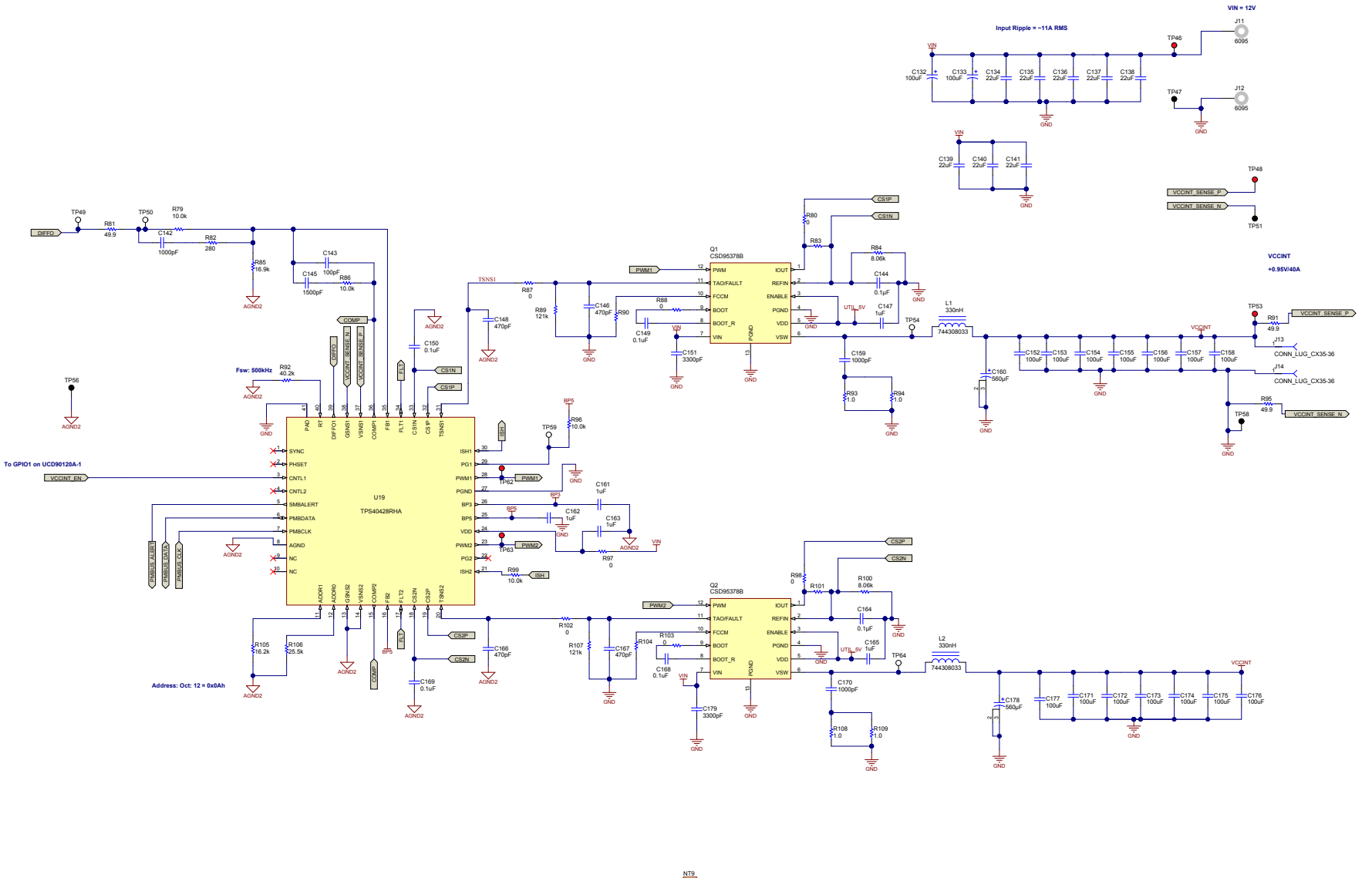
Designed for: Public Release		Mod. Date: 6/27/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: Cover Sheet	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 1 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_Cover.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

Sequencer/System Monitor #1



Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: Sequencer 1	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 2 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_Sequencer-1.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

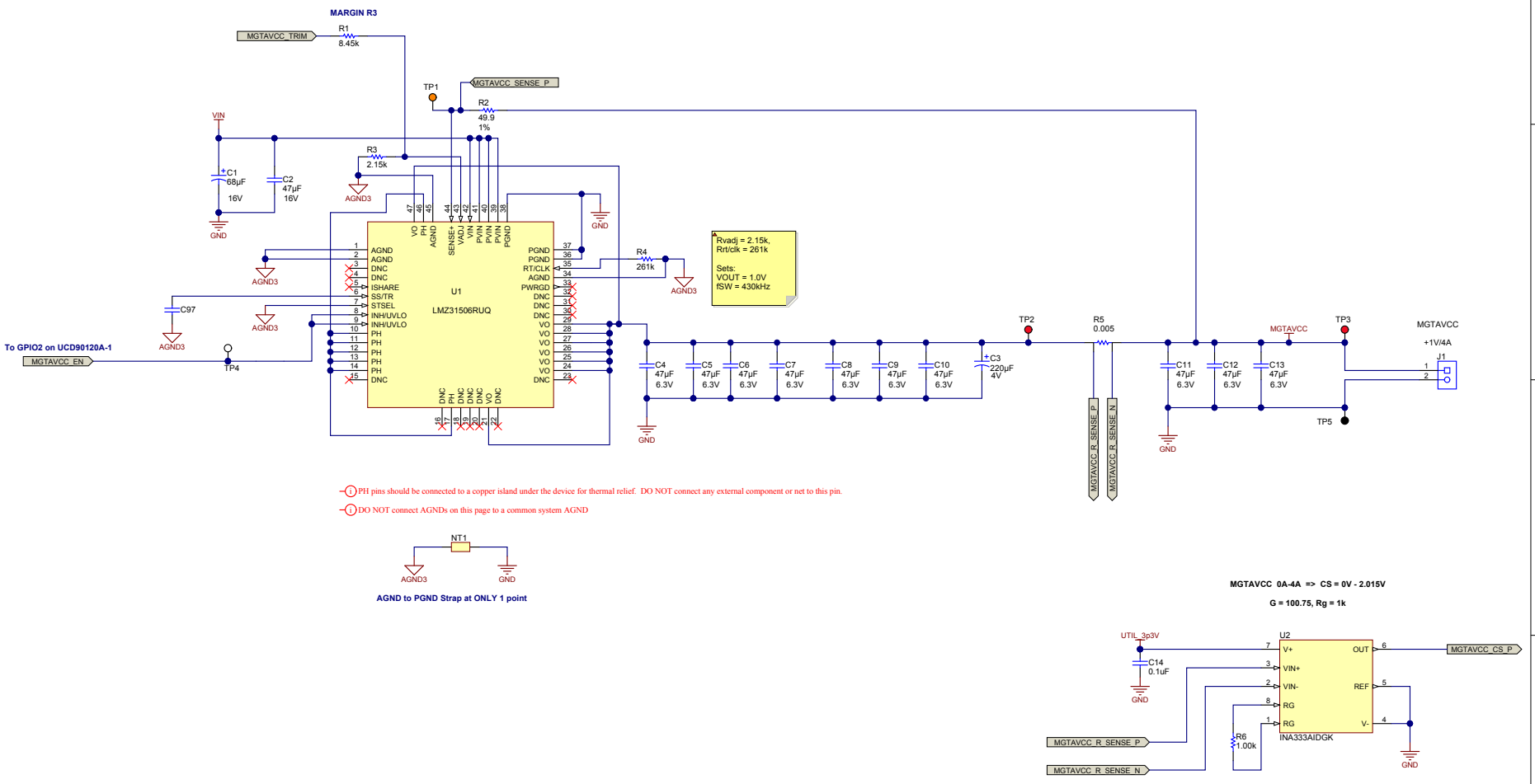
VCCINT: 0.95V@40A



Number: PMP9444	Rev: E2
SVN Rev: Not in version control	
Drawn By: Sami Sirhan	
Engineer: Sami Sirhan	

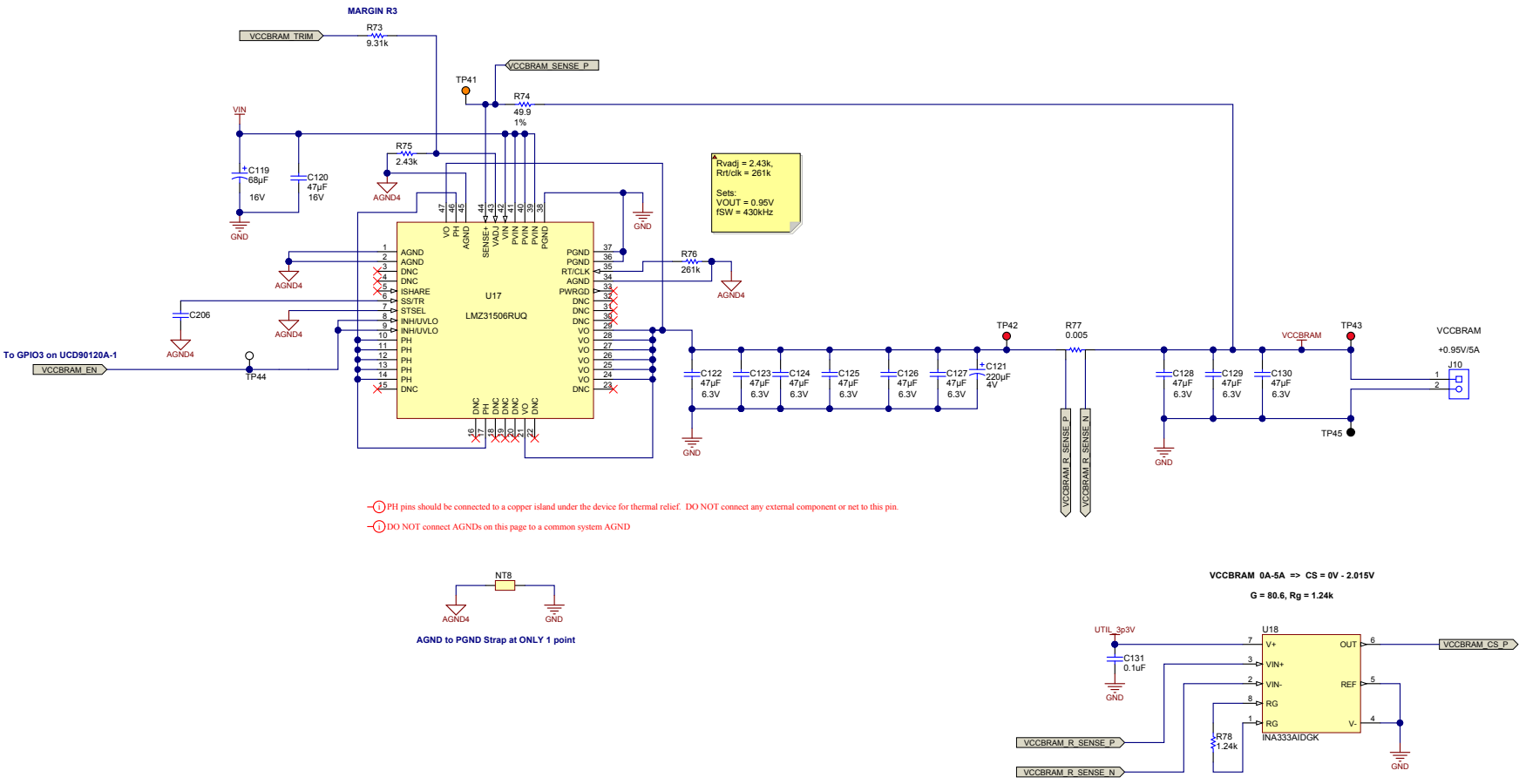
Designed for: Public Release	Mod. Date: 6/19/2014
Project Title: Xilinx Ultrascale Kintex Power Ref Design	
Sheet Title: VCCINT	
Assembly Variant: [No Variations]	Sheet: 3 of 15
File: SAY01015Z_VCCINT_0p95V_40A.SchDoc	Size: C
Contact: http://www.ti.com/support	http://www.ti.com

MGTAVCC 1.0V @ 4A



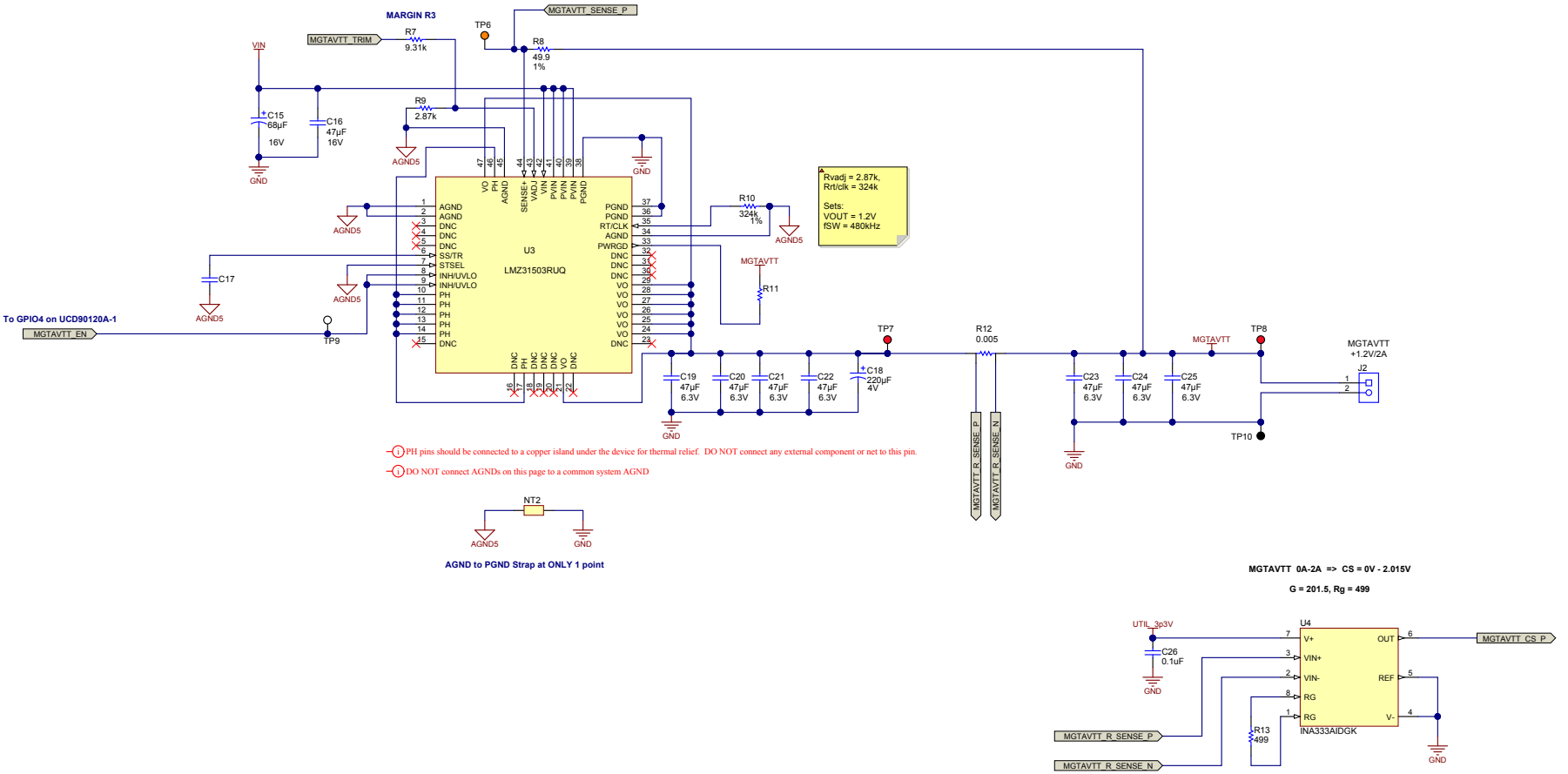
Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: MGTAVCC	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 4 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_MGTAVCC_1p0V_4A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

VCCBRAM 0.95V @ 5A



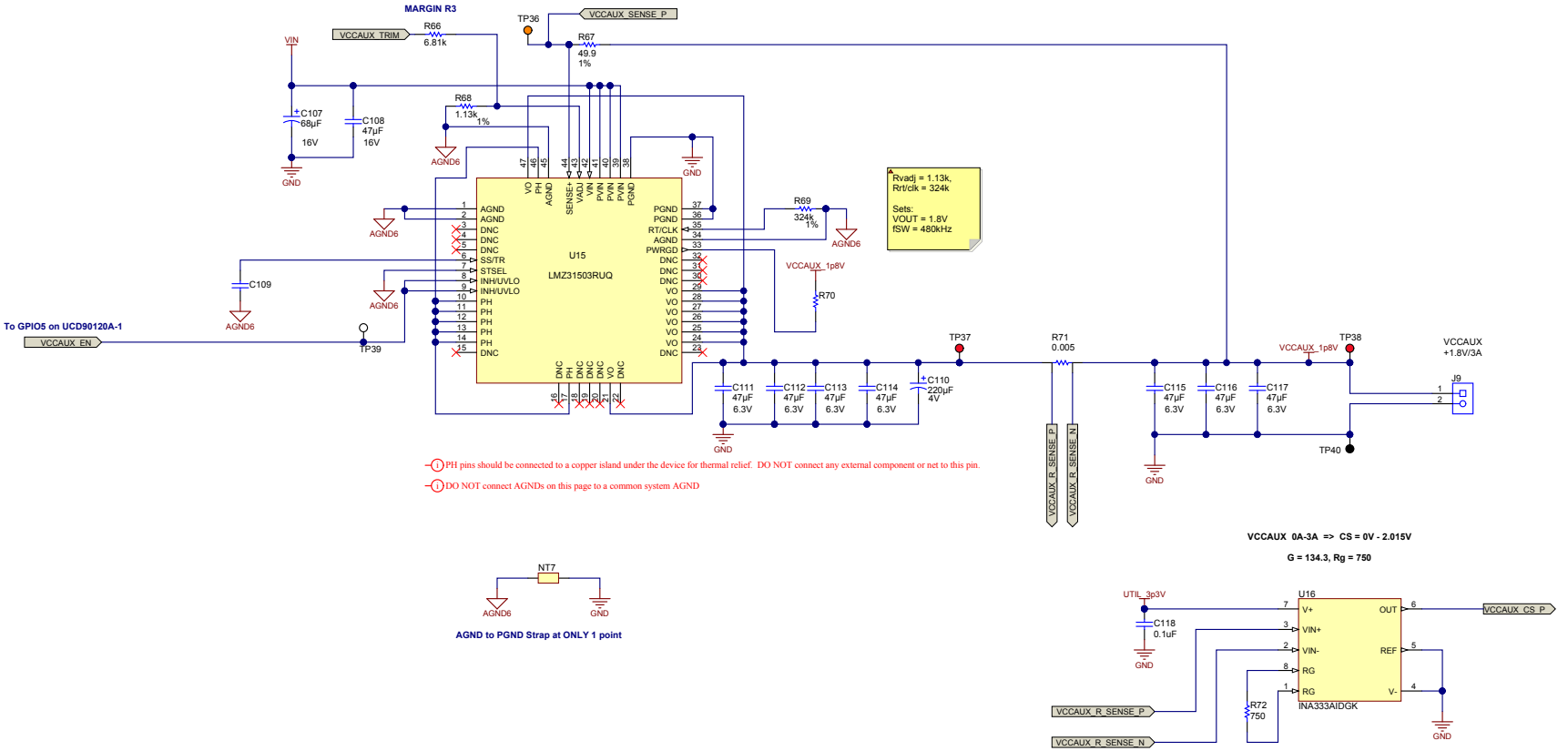
Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: VCCBRAM	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 5 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_VCCBRAM_0p95V_5A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

MGTAVTT: 1.2V @ 2A



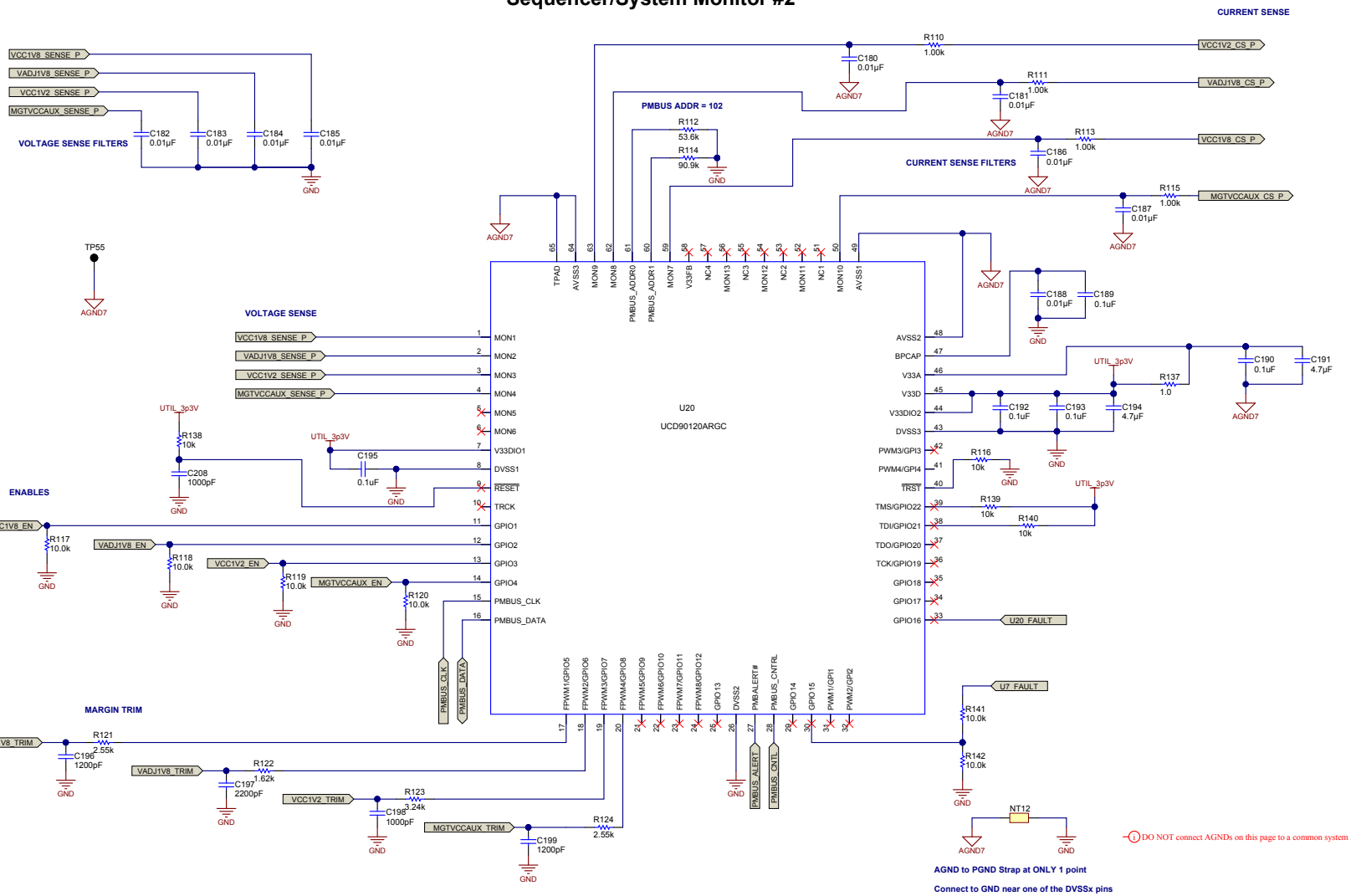
Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: MGTAVTT	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 6 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_MGTAVTT_1p2V_2A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

VCCAUX: 1.8V @ 3A



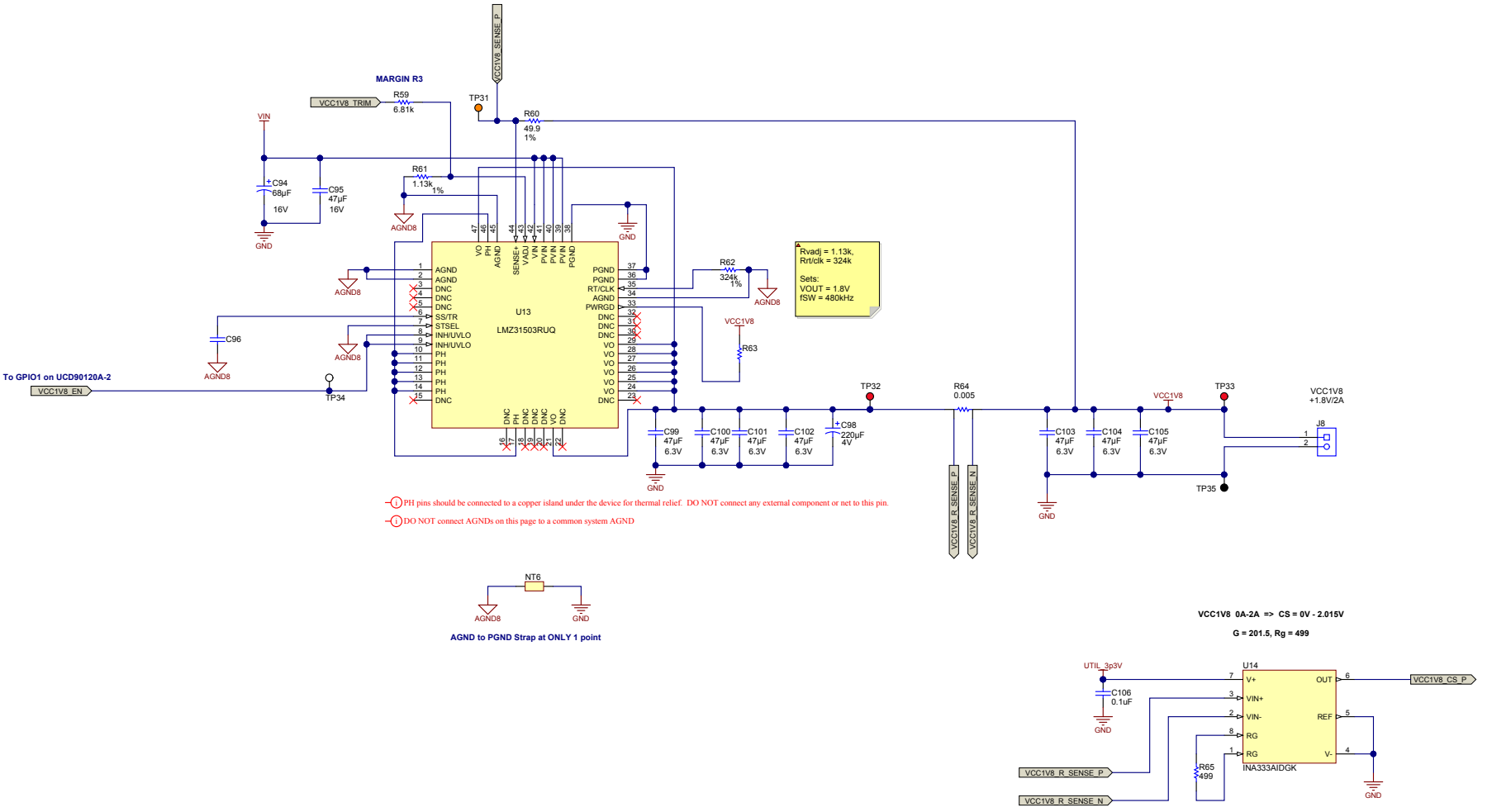
Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: VCCAUX	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 7 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_VCCAUX_1p8V_3A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

Sequencer/System Monitor #2



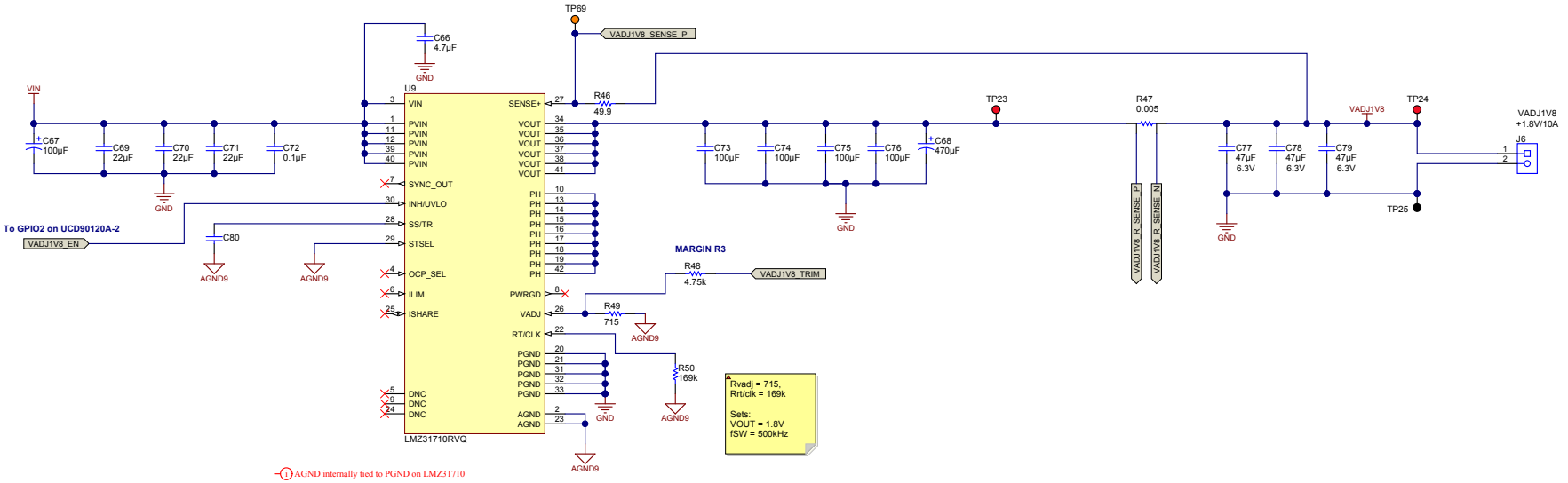
Designed for: Public Release	Mod. Date: 6/19/2014		
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: Sequencer 2	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 8 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_Sequencer-2.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

VCC1V8: 1.8V @ 2A



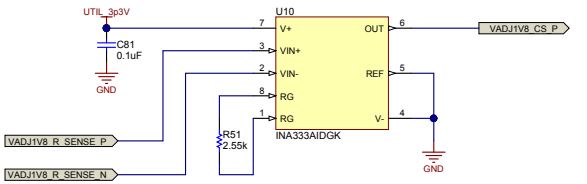
Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: VCC1V8	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 9 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_VCC1V8_1p8V_2A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

VADJ1V8: 1.8V @ 10A



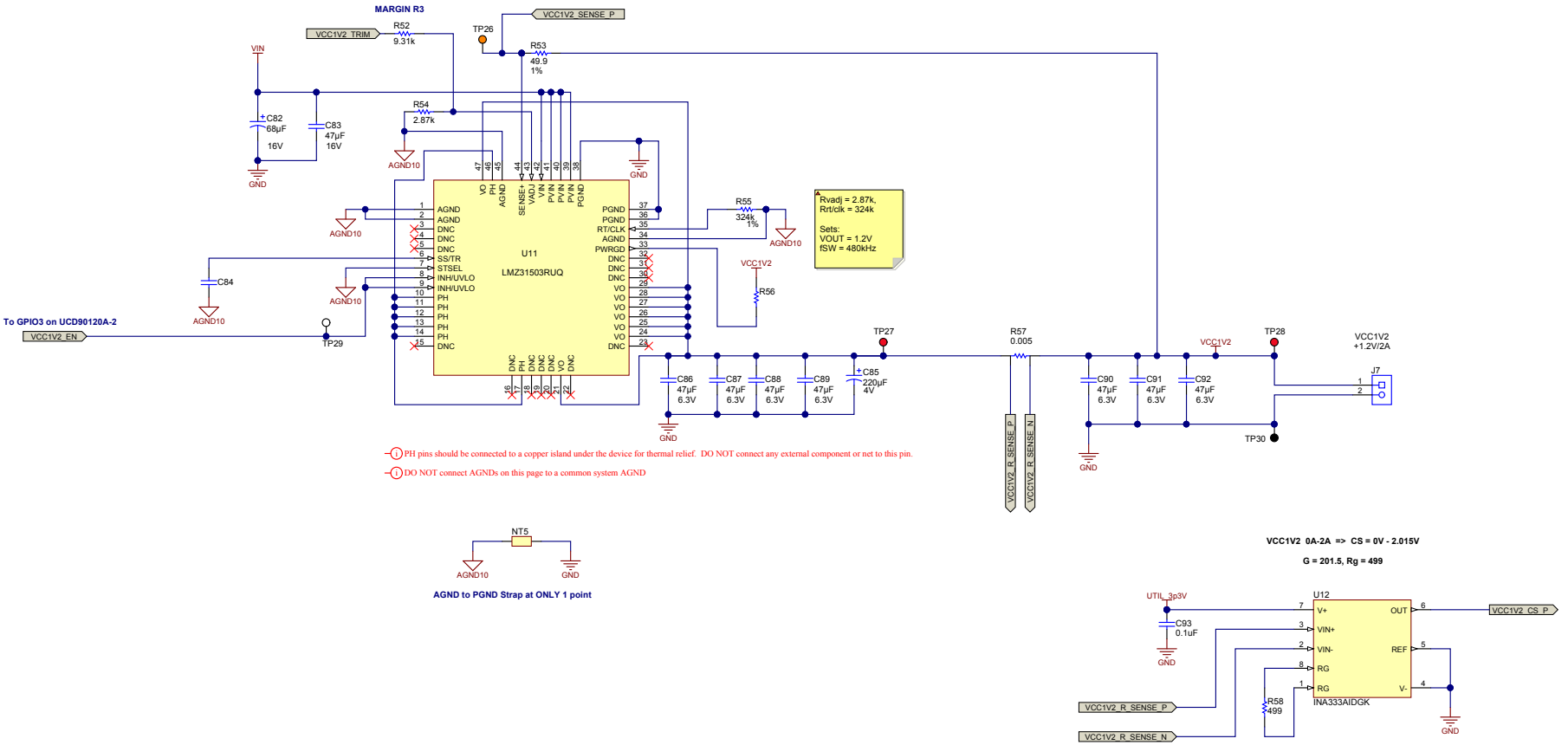
VADJ1V8 0A-10A => CS = 0V - 2.015V

G = 40.3, Rg = 2.55k



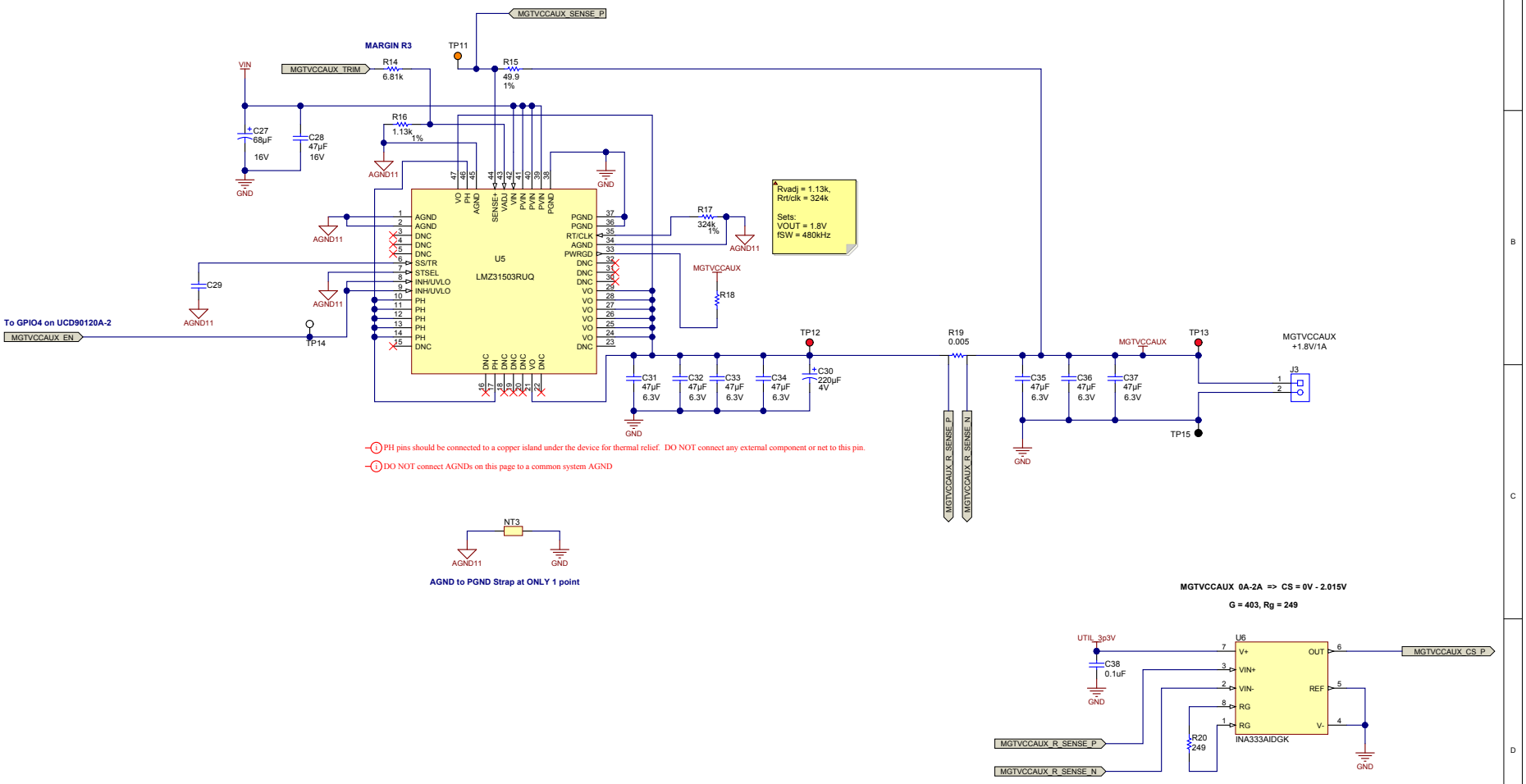
Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: VADJ	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 10 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_VADJ_1p8V_10A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

VCC1V2: 1.2V @ 2A



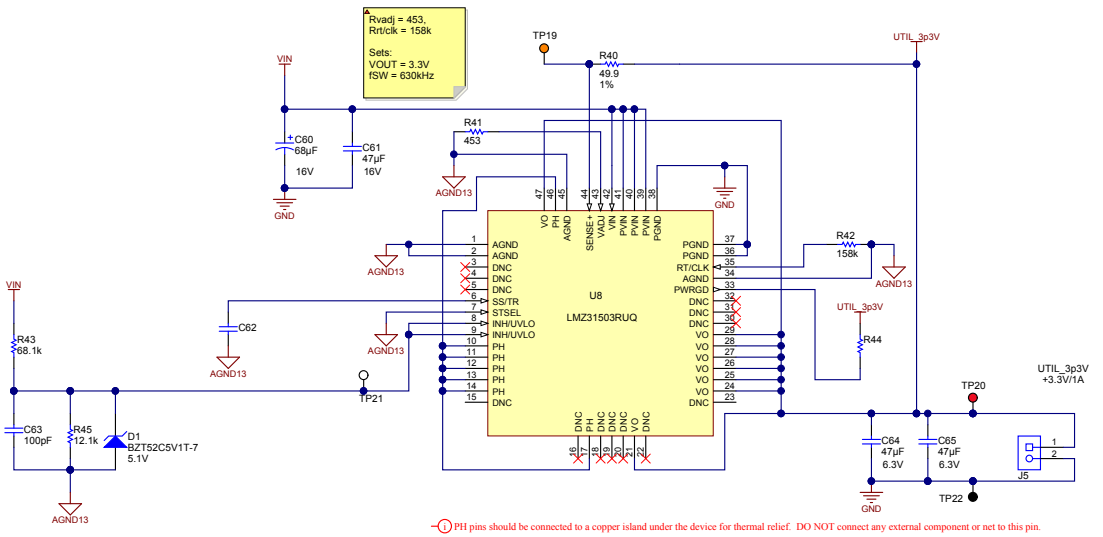
Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: VCC1V2	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 11 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_VCC1V2_1p2V_2A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

MGTVCCAUX: 1.8V @ 1A



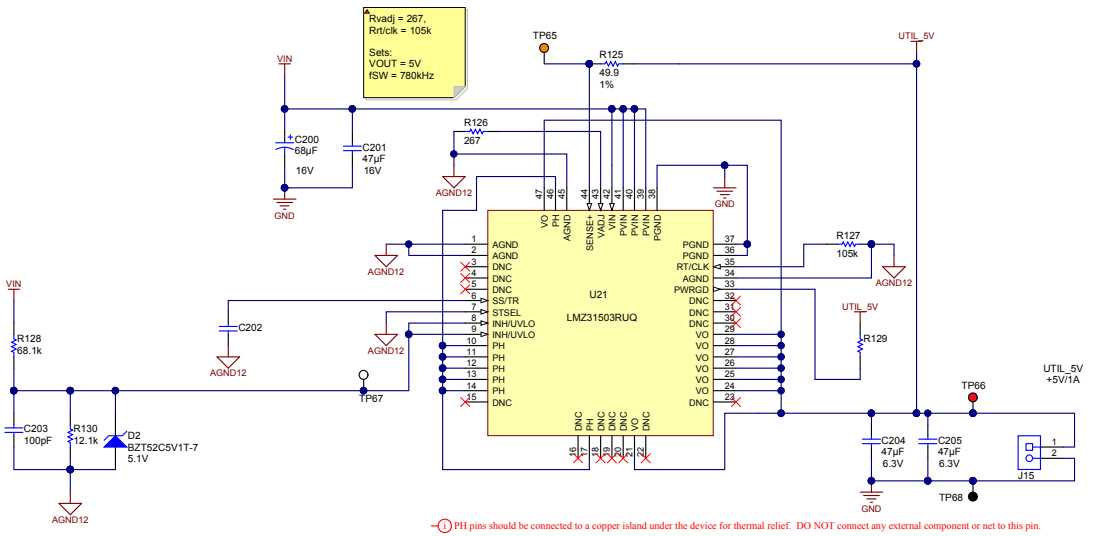
Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: MGTVCCAUX	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 12 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_MGTVCCAUX_1p8V_1A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

UTIL_3p3V: 3.3V @ 1A



Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: UTIL_3P3V	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 13 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_UTIL_3p3V_1A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

UTIL_5V: 5V @ 1A



Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: UTIL_5V	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 14 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_UTIL_5V_1A.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

H1
NY PMS 440 0025 PH

H2
NY PMS 440 0025 PH

H3
NY PMS 440 0025 PH

H4
NY PMS 440 0025 PH

H5
1902C

H6
1902C

H7
1902C

H8
1902C

FID1 FID2 FID3

FID4 FID5 FID6

PCB Number: PMP9444
PCB Rev: E2

PCB
LOGO
Texas Instruments

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Designed for: Public Release		Mod. Date: 6/19/2014	
Project Title: Xilinx Ultrascale Kintex Power Ref Design			
Number: PMP9444	Rev: E2	Sheet Title: Hardware	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 15 of 15
Drawn By: Sami Sirhan		File: SAT0101E2_Hardware.SchDoc	Size: B
Engineer: Sami Sirhan		Contact: http://www.ti.com/support	http://www.ti.com

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